

## **Amendments to the Claims:**

This listing of claims will replace all previous versions of the claims:

1. (Previously Presented) A circuit module comprising:
  - a circuit substrate having a first wiring pattern provided on a first surface on one side thereof and a second wiring pattern provided on a second surface on another side thereof;
  - a first flip chip component mounted on the first surface; and
  - a second flip chip component mounted on the second surface,wherein an insulation layer is formed on the first or second surface such that the insulation layers substantially entirely covers the first or second surface and wherein the first or second flip chip component is embedded in the insulation layer.
2. (Original) A circuit module according to Claim 1, wherein an exposed surface of the insulation layer is a flat surface that is in parallel with the first or second surface.
3. (Previously Presented) A circuit module according to Claim 1, wherein an electrical component is mounted on the first surface in addition to the first flip chip component and wherein the second flip chip component mounted on the second surface is embedded in the insulation layer.
4. (Previously Presented) A circuit module according to Claim 3, wherein a terminal portion is formed on the second surface in a state in which the terminal portion is connected to the second wiring pattern and wherein the terminal portion is embedded in the insulation layer with an end face thereof exposed.
5. (Original) A circuit module according to Claim 4, wherein the terminal portion can be connected to a conductive pattern on a mother substrate with a surface of the insulation layer placed on the mother substrate.
- 6-9. (Cancelled)